

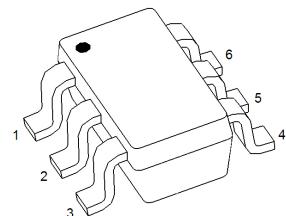
# **SOT-23-6 Plastic-Encapsulate MOSFETS**

**8820**

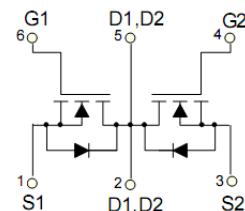
## **8820 Dual N-Channel MOSFET**

<b>V<sub>(BR)DSS</sub></b>	<b>R<sub>D(on)MAX</sub></b>	<b>I<sub>D Max</sub></b>
20V	0.014 Ω @ 4.5V	6.0A
	0.018 Ω @ 2.5V	

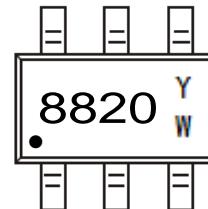
### **SOT-23-6**



### **Equivalent Circuit**



### **MARKING**



Y :year code    W :week code

### **ABSOLUTE MAXIMUM RATINGS (T<sub>a</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Continuous Drain Current	I <sub>D</sub>	6	A
Pulsed Drain Current (note 1)	I <sub>DM</sub>	25	A
Thermal Resistance from Junction to Ambient (note 2)	R <sub>θJA</sub>	100	°C/W
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature	T <sub>STG</sub>	-55~+150	°C
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	T <sub>L</sub>	260	°C



SHENZHEN TUOFENG SEMICONDUCTOR TECHNOLOGY CO.,LTD

# SOT-23-6 Plastic-Encapsulate MOSFETS

**8820**

## MOSFET ELECTRICAL CHARACTERISTICS

T<sub>a</sub> = 25 °C unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC CHARACTERISTICS</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	20			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 19V, V <sub>GS</sub> = 0V			100	nA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V			±100	nA
Gate threshold voltage (note 3)	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.5		1.0	V
Drain-source on-resistance (note 3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 6A	9.0	12.5	14	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 5.5A	12.0	15.5	18	mΩ
Forward transconductance (note 3)	g <sub>F</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 6A		10		S
Diode forward voltage (note 3)	V <sub>SD</sub>	I <sub>S</sub> = 1.50A, V <sub>GS</sub> = 0V			1.0	V
<b>DYNAMIC CHARACTERISTICS (note 4)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1MHz		615		pF
Output Capacitance	C <sub>oss</sub>			150		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			120		pF
<b>SWITCHING CHARACTERISTICS (note 4)</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GS</sub> = 5V, V <sub>DS</sub> = 10V, R <sub>L</sub> = 1.4Ω, R <sub>GEN</sub> = 3Ω		7.2		ns
Turn-on rise time	t <sub>r</sub>			13		ns
Turn-off delay time	t <sub>d(off)</sub>			29		ns
Turn-off fall time	t <sub>f</sub>			11		ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 6A		12		nC
Gate-Source Charge	Q <sub>gs</sub>			1.2		nC
Gate-Drain Charge	Q <sub>gd</sub>			3.0		nC

**Notes :**

1. Repetitive rating: Pulse width limited by maximum junction temperature
2. Surface Mounted on FR4 board, t ≤ 10 sec.
3. Pulse test : Pulse width ≤ 300μs, duty cycle ≤ 2%.
4. Guaranteed by design, not subject to production.

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS:

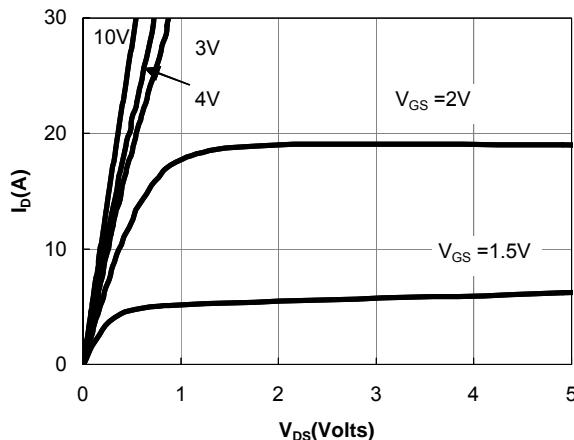


Figure 1: On-Regions Characteristics

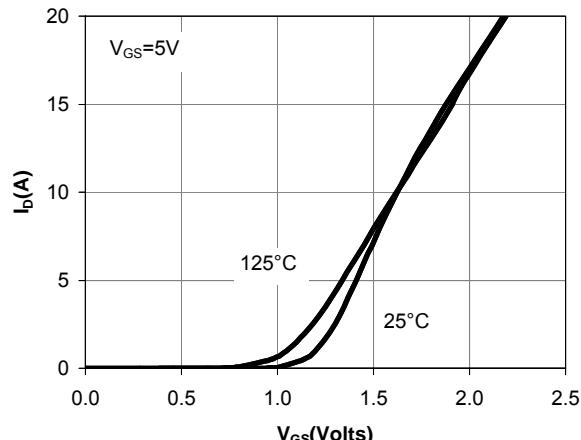
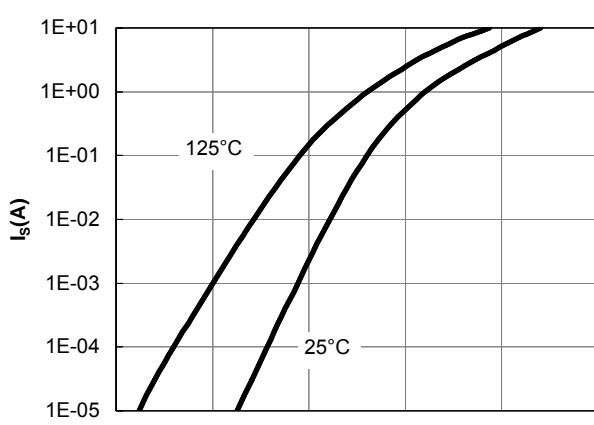
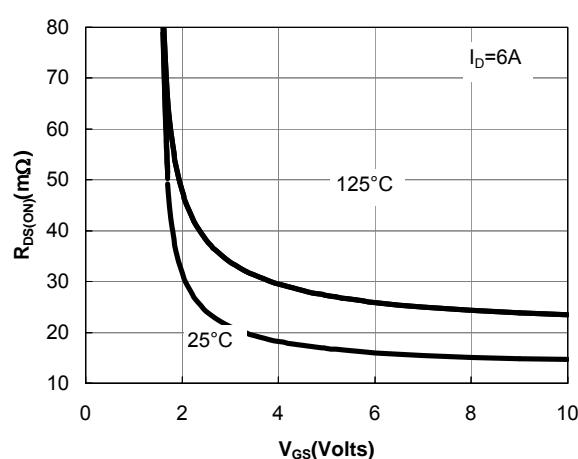
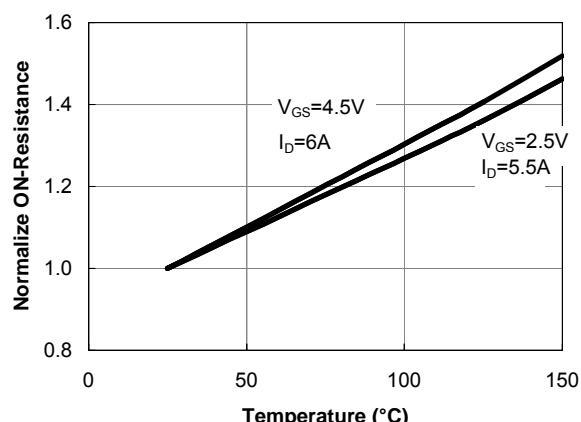
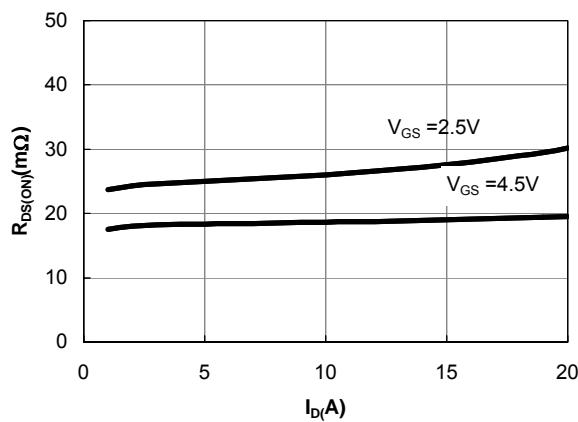


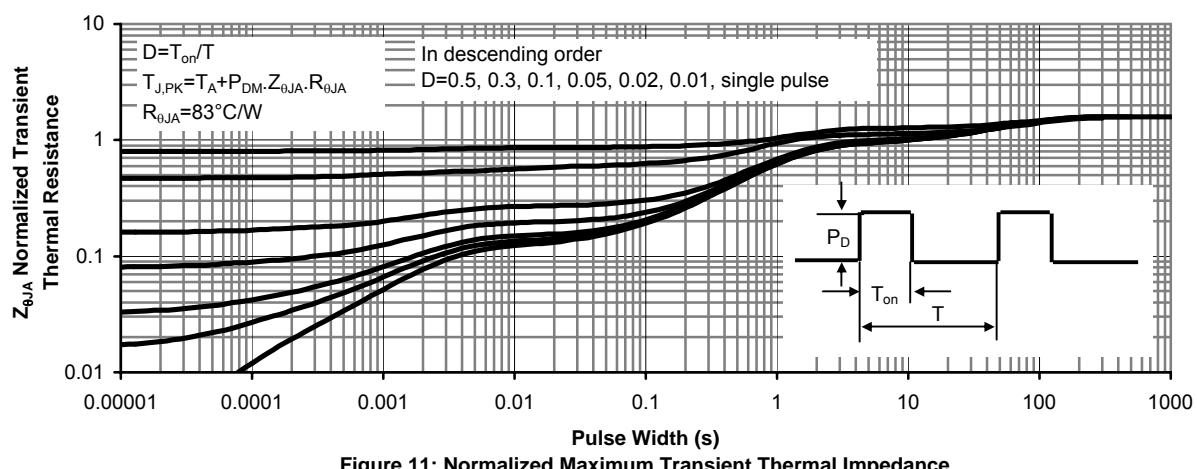
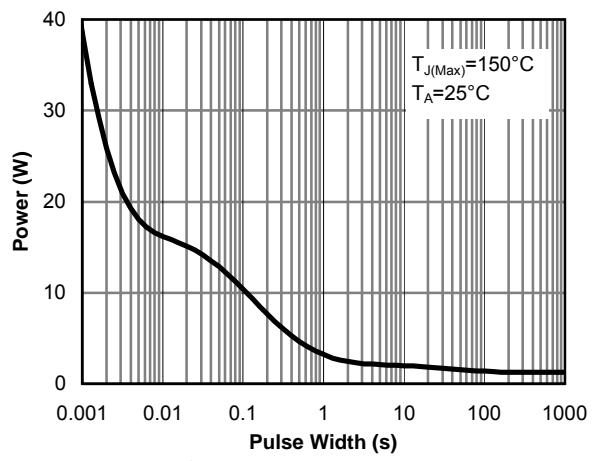
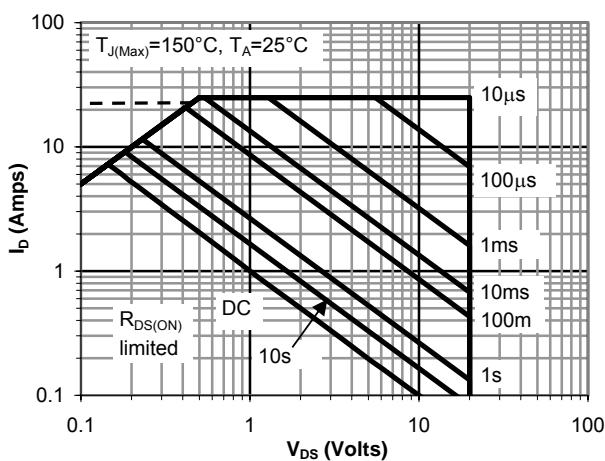
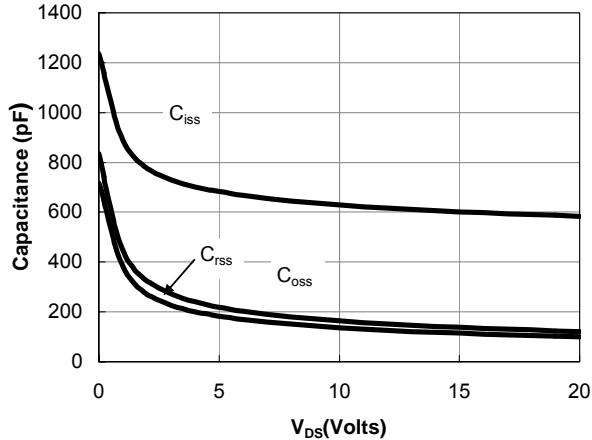
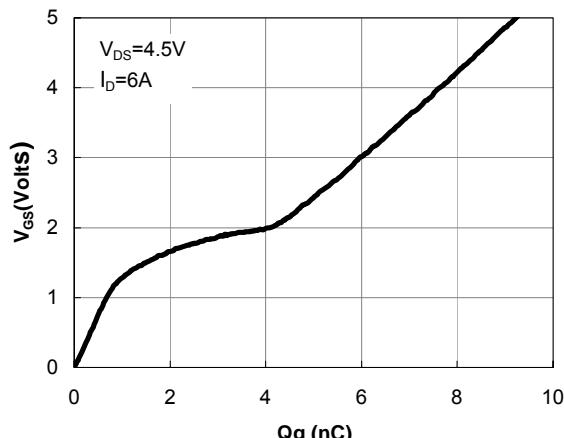
Figure 2: Transfer Characteristics



# SOT-23-6 Plastic-Encapsulate MOSFETs

**8820**

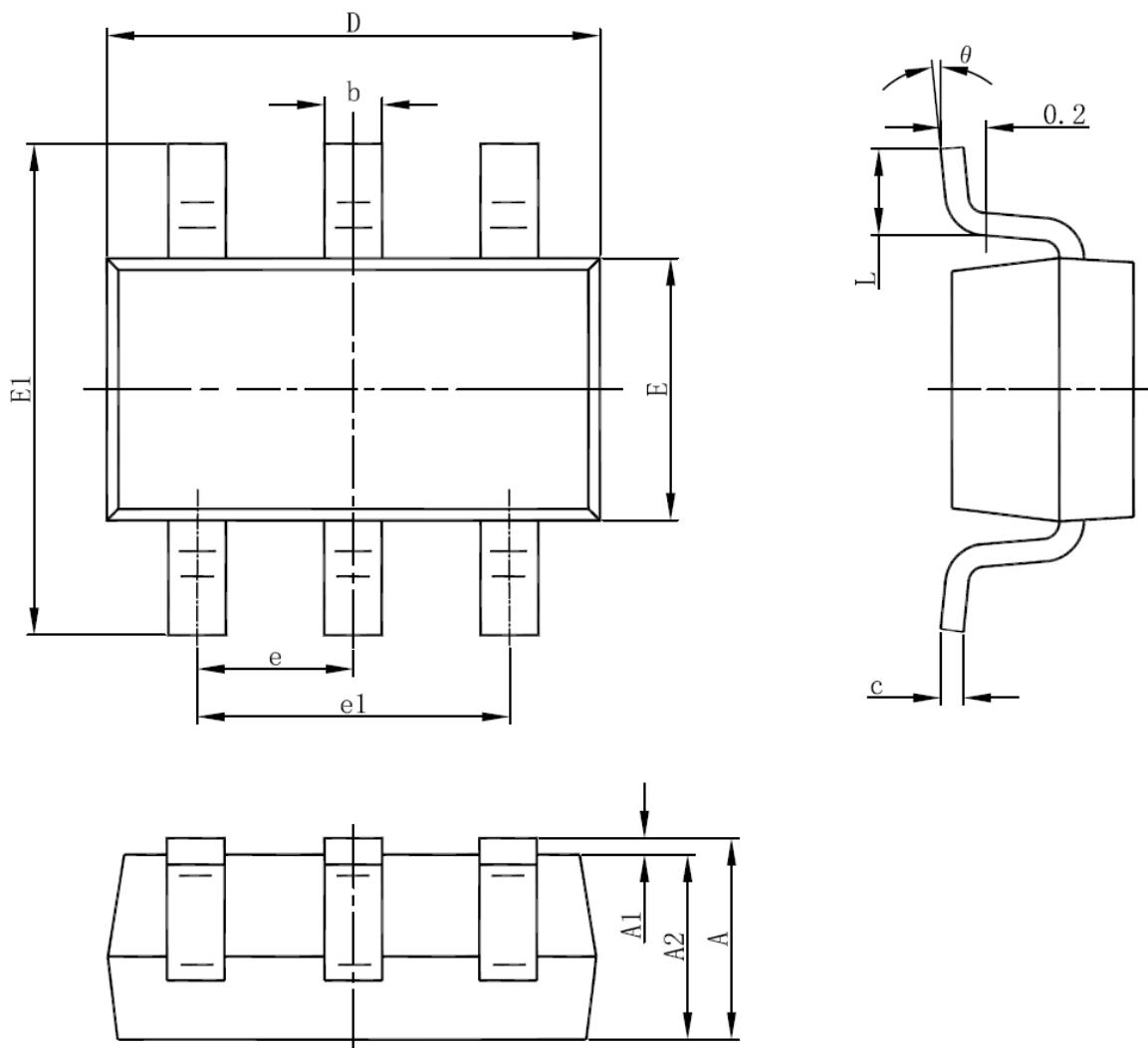
## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS<sup>1</sup>



# SOT-23-6 Plastic-Encapsulate MOSFETs

**8820**

## SOT23-6 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°